

ABSTRACT

This invention concerns a manufacturing method for an electronic module and a module manufactured according to this method that includes an assembly with two insulating sheets (2, 9) and an electronic element (3). A first insulating sheet (2) constituting one of the faces of the module including at least one window (4) in which the electronic element (3) is housed, one face of said element (3) levelling the surface of said first sheet (2) and appearing on the exterior face of the module. The second insulating sheet (9) constitutes the other face of the module. The module is characterized in that it includes an adhesive film (5) which extends over a region covering at least the outline of the window (4) of the element (3) and is situated in a region situated between the first sheet (2) and the second sheet (9).

The module can also include at least one electronic circuit (6) placed between the two insulating sheets (2, 9) and connected to the element (3) on the conductive connection areas (13) located on the interior face of the element (3).

The aim of this invention consists in avoiding the appearance of undesirable residues on the exterior face of the module in the vicinity of the element (3). These residues that originate from the infiltration of a filling material (8) through the window (4) and/or the element (3) which is housed there.